

I've removed my address due to privacy concerns. I'm currently located in Austin, TX.

Michael C. Hollinger

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- OBJECTIVE** Full-time leadership position in device-level / embedded software, and / or digital convergence hardware and software. Very interested in augmented reality and mobile applications, as well as enterprise systems development.
- EDUCATION**
- 08 / 04 – 05 / 05 University of Oklahoma, Norman OK – Accel. M.S. Electrical Engr. / Computer Engr.
- Thesis Defended: *Server-Side Software For Multimodal User Interactions*
 - May, 2005 Graduation (M.S. Electrical and Computer Engineering)
 - 3.5 / 4.0 GPA with Thesis Option
- 08 / 00 – 05 / 04 University of Oklahoma, Norman, OK – B.S. Computer Engineering
- Summa Cum Laude, 3.8 / 4.0 GPA, including 16 hours honors credit
 - **Applicable Courses:** Engineering Leadership / Org. Management, Computer Architecture, Computer Hardware Design, Data Structures, E.E. Labs & Design Lab, Microprocessor Design, Signals and Systems, Robotics, Reconfigurable Computing, A.I.
- HONORS / ACTIVITIES**
- Outstanding Innovation Award, EnergyScale
 - 18 Patents Filed, 2 Patents Granted
 - Leadership Team, IBM Austin Emerging Technology & Business Innovation Board
 - Member, Out@IBM GLBT Diversity Network
 - 2004-05 Co-Chair IEEE OU Tech. Society
 - 2003-05 President, Eta Kappa Nu Electrical & Computer Engineering OU Honor Society
 - '04 Outstanding Senior in Computer Engr.
 - Tau Beta Pi Engineering Honor Society
- SKILLS**
- Embedded SW Architecture
 - C / C++
 - Digital Circuit Design
 - VHDL
 - Bringup of Complex, Integrated Systems
 - Renesas H8 & SH IDE
 - Presentation / Communication Skills
 - Java
 - SQL, MySQL
 - X+V, VoiceXML
 - H8, SH4A, and 68HC11 Assembly
 - Linux & Windows Dev.
 - Energy Management SW
 - Embedded Linux
 - Web App Design

WORK EXPERIENCE

12/08 – Current	IBM, Systems & Technology Group, Power Firmware Development	<i>System Functional Owner, Power 750 / Power 755 Compute Node</i>	Austin, TX
<ul style="list-style-type: none">• System Firmware Platform Lead for the IBM Power Systems 750 / 755, the first shipping server for the POWER7 processor.• Led firmware bringup across multiple subsystems, brokered deals with external groups, educated peers on new technologies.• Delivered firmware drivers on-time, and met manufacturing, system test, and external “extreme” early ship commitments.• Achieved platform stability several months ahead of schedule, working closely with Chief Engineer and FW Release Architect.• Primary Author / Editor, “IBM EnergyScale for POWER7 Processor-Based Systems” White Paper.			
06/06 – 12/08	IBM, Systems & Technology Group, EnergyScale™ Technology	<i>Embedded Systems Developer, Power-Aware Firmware</i>	Austin, TX
<ul style="list-style-type: none">• Architected and implemented real-time firmware for power management technologies on IBM Power Systems platforms, including the JS22 “POWER6” Blade, Power 520, Power 550, Power 575, and Power 595.• Productized algorithms from IBM Research for real-time performance-aware power management (Dynamic Power Optimizer) on systems with real-time Thermal / Power Management controllers (TPMD-enabled systems such as POWER 550).• Evangelized energy-efficient technology within the company, and to customers (e.g. http://www.youtube.com/watch?v=t2Bbm4tI_Ftl).			
06/05 – 06/06	IBM, Systems & Technology Group, Job Rotation Program	<i>Bringup Engineer, POWER6 Servers; Embedded Systems Coding</i>	Austin, TX
<ul style="list-style-type: none">• First power-on of POWER6-based System p 570 systems, focusing on integration of firmware with POWER6 and the PowerVM.• Identified and debugged a variety of problems in the service processor firmware, system initialization, and system hardware.• Led firmware efforts to achieve power-on and stability of the largest-configuration of the p570 at the time.			
05/04 – 08/04 & 08/04 – 05/05 (co-op)	IBM, Extreme Blue Program Team Outspoken	<i>Customer-Facing Application Creation</i>	Austin, TX
<ul style="list-style-type: none">• Created prototype solutions that demonstrate to customers and partners the functionality and business advantages of IBM Multimodal Technology with a combined team of technical and business co-ops.• Co-Inventor of models for X+V / Multimodal applications leading to seven patent applications filed with the USPTO.• Designed market entry strategy for IBM multimodal technology in the cellular space.			